

Effect of moisture content and its distribution throughout the mat on thick waferboard

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Contributor: Forintek Canada Corp.
Date: March 1981
Material Type: Research report
Physical Description: 17 p.
Sector: Wood Products
Field: Wood Manufacturing & Digitalization
Research Area: Advanced Wood Manufacturing
Subject: Waferboards

Physical properties

Panels

Binders

Series Number: Forestry Canada no. 34
E-1564

Location: Ottawa, Ontario

Language: English

Abstract: The relationship of press closing time, strength properties and density profile of thick waferboard panels to mat moisture content was demonstrated in this study. Lower mat moisture contents were found to increase press clothing time but permit faster binder curing. When the distribution of mat moisture was higher in the face layers, shorter press times were achievable and a significant densification of the panel was observed.

Waferboard - Panels - Physical Properties

Moisture content

Binders

Curing

Documents



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